US00D937340S

(12) **United States Design Patent** (10) **Patent No.: US D937,340 S**
Shain (45) **Date of Patent: ** Nov. 30, 2021**

(54) **SENSOR MODULE**

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(73) Assignee: **FLIR Systems, Inc.**, Wilsonville, OR (US)

(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **16-05**

(52) **U.S. Cl.**
USPC **D16/219**

(58) **Field of Classification Search**
USPC D10/52, 60; D16/136, 200, 219; D14/217
CPC H01R 13/6275; H01R 43/26; H01R 13/5219; G01J 5/0806; G01J 5/10; G01J 1/0233; G01J 5/0809; H04N 5/23203; H04N 5/33; H04N 5/332; H04N 5/335; H04N 5/2252; H04N 7/183; G08B 13/19632; G08B 13/19619
See application file for complete search history.

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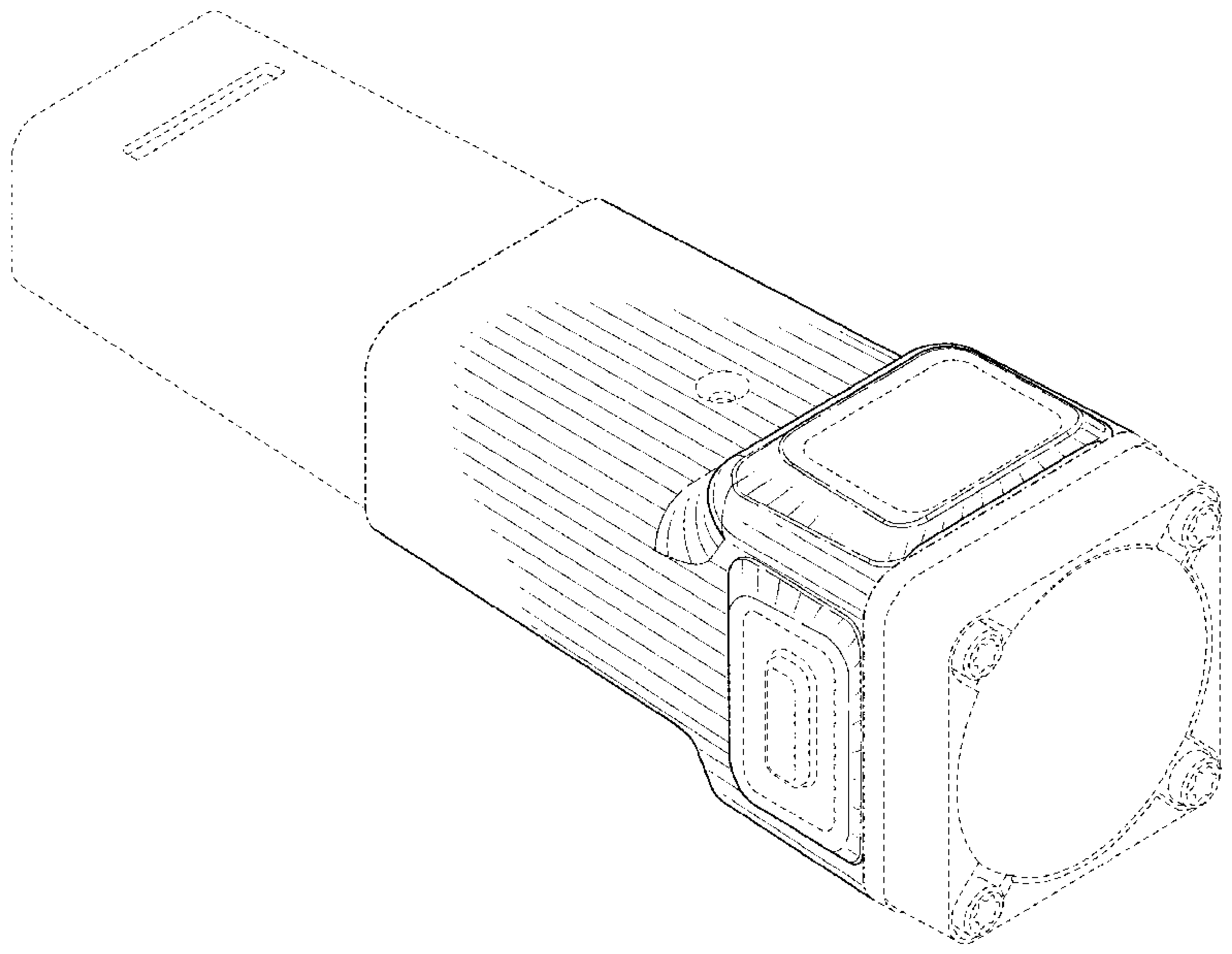
(57) **CLAIM**

The ornamental design for a sensor module, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, and right perspective view of a sensor module embodying the new design;
FIG. **2** is a rear, bottom, and left perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a rear elevational view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is a top plan view thereof; and,
FIG. **8** is a bottom plan view thereof.
The broken lines in the drawings illustrate portions of the sensor module and form no part of the claimed design. The dot-dash-dot broken lines in the drawings define the bounds of the claim and form no part thereof.

1 Claim, 5 Drawing Sheets



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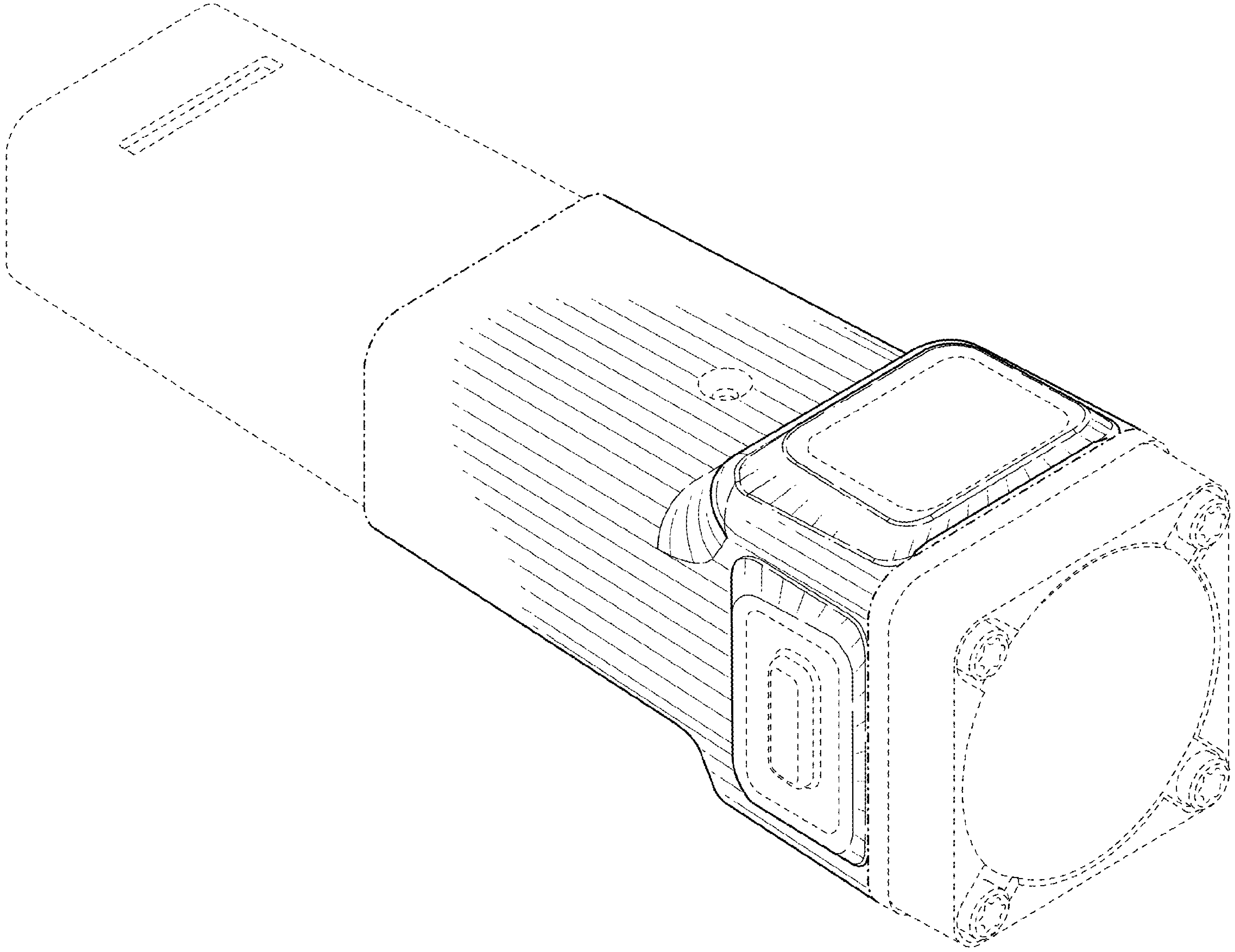

FIG. 1

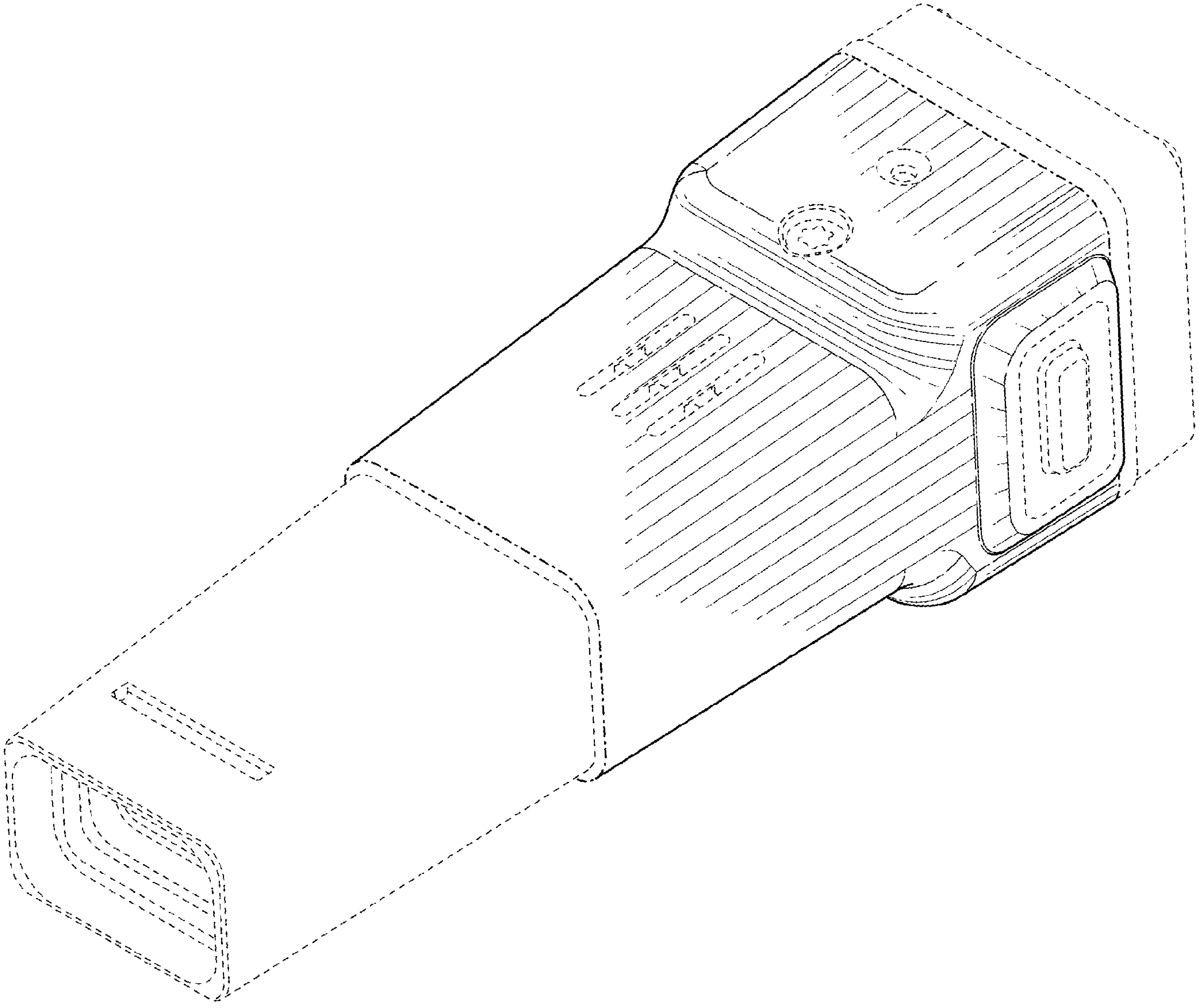

FIG. 2

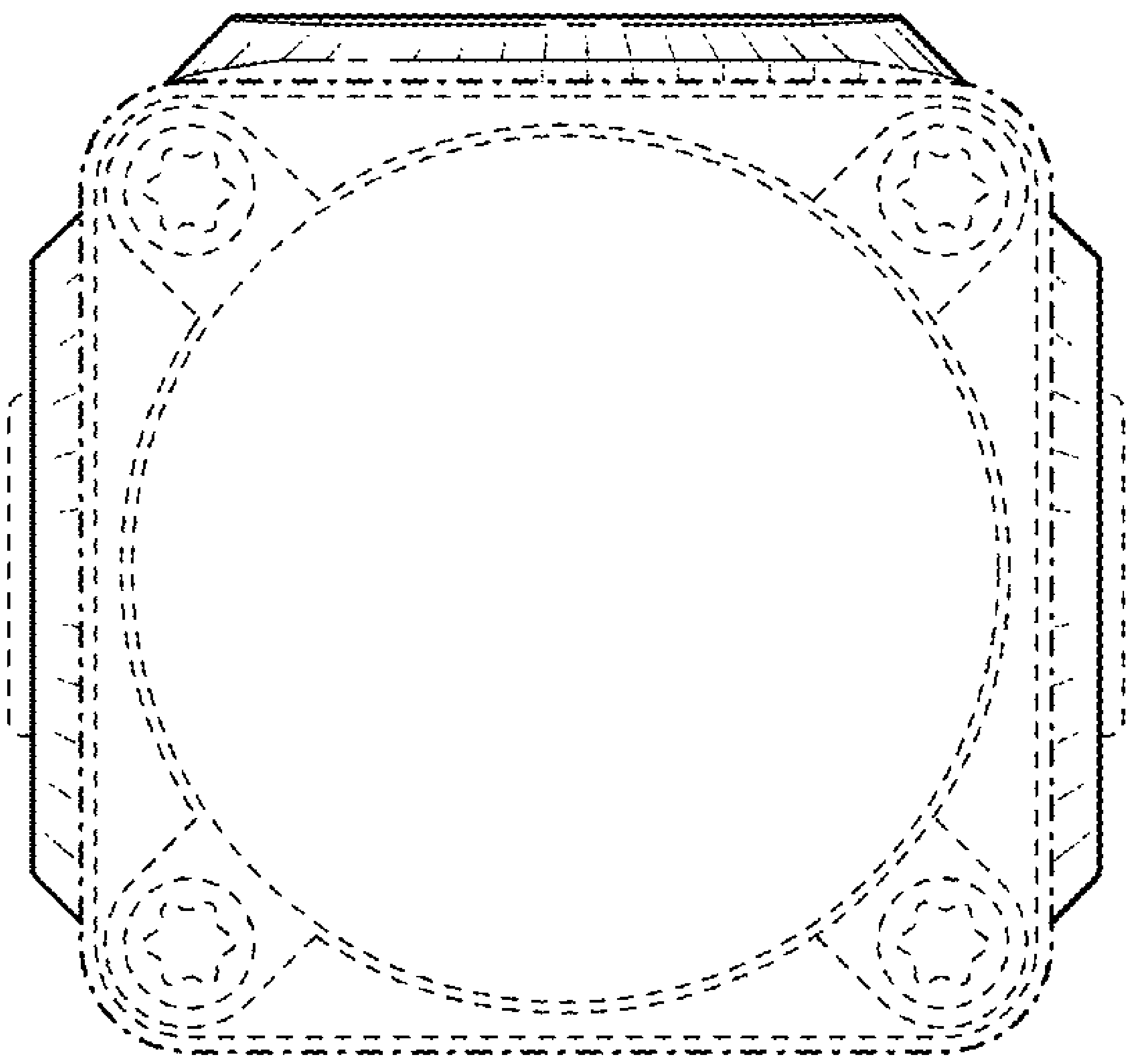

FIG. 3

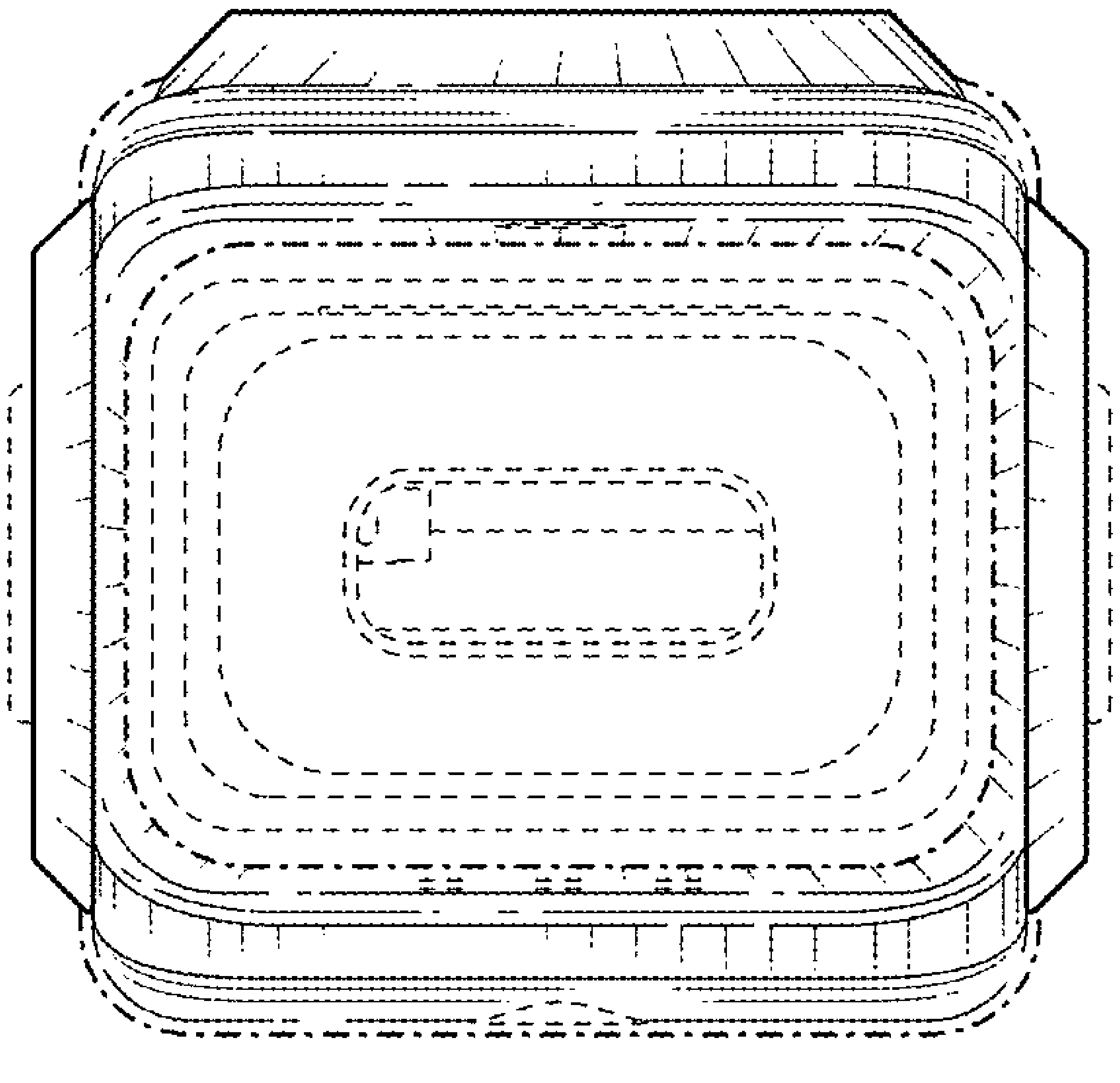

FIG. 4

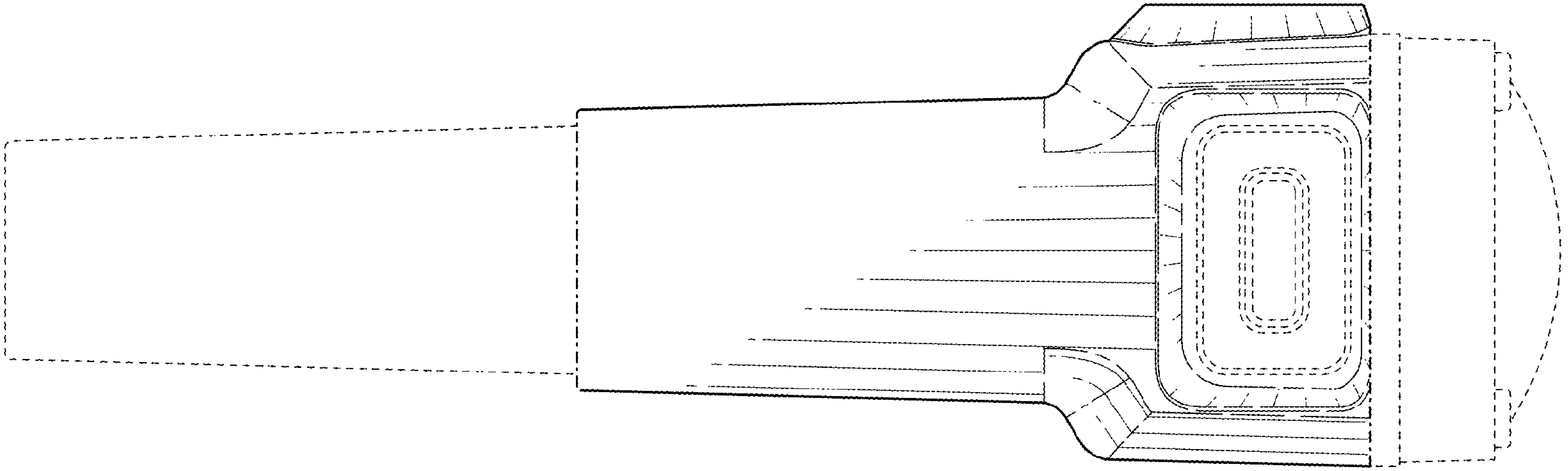

FIG. 5

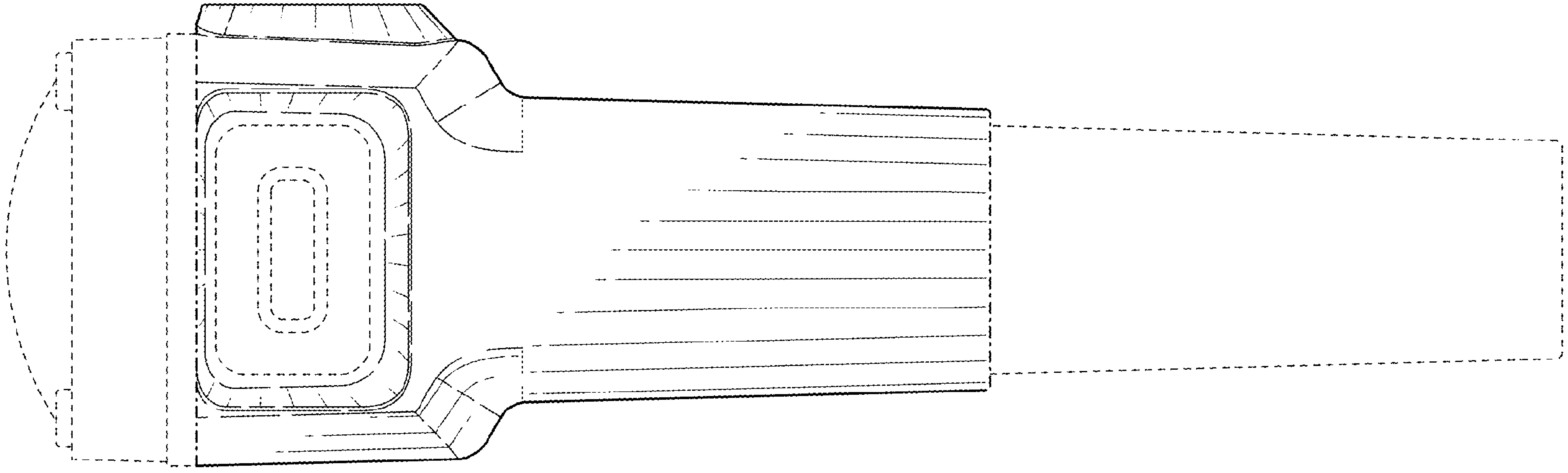

FIG. 6

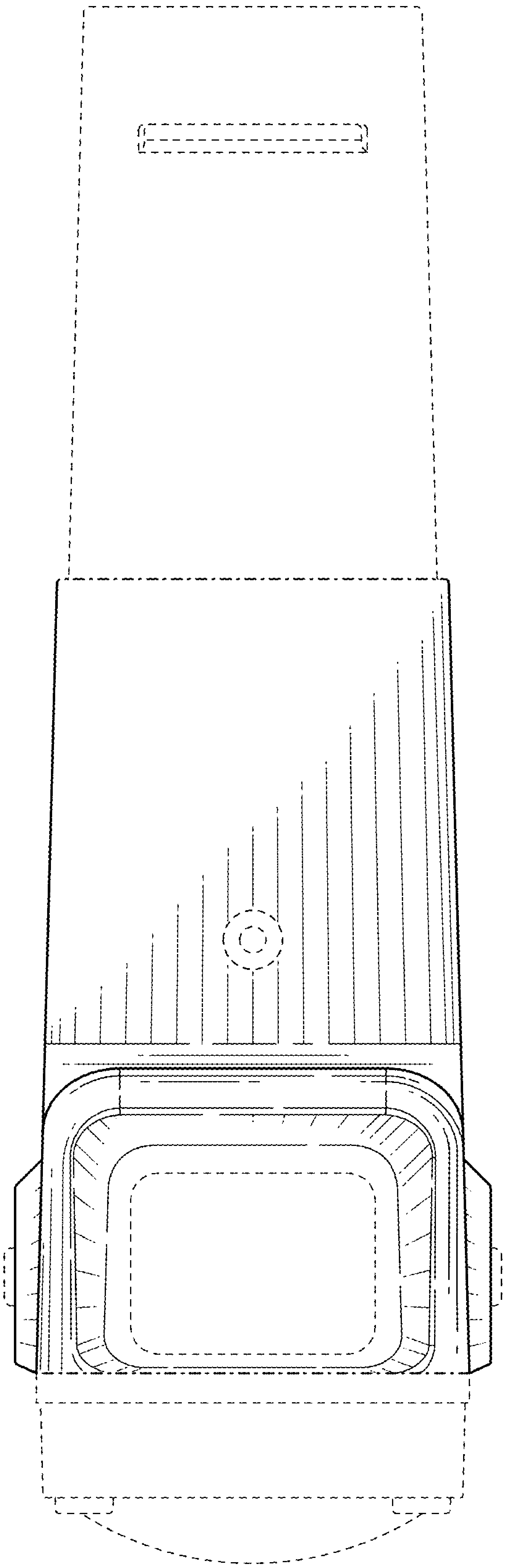

FIG. 7

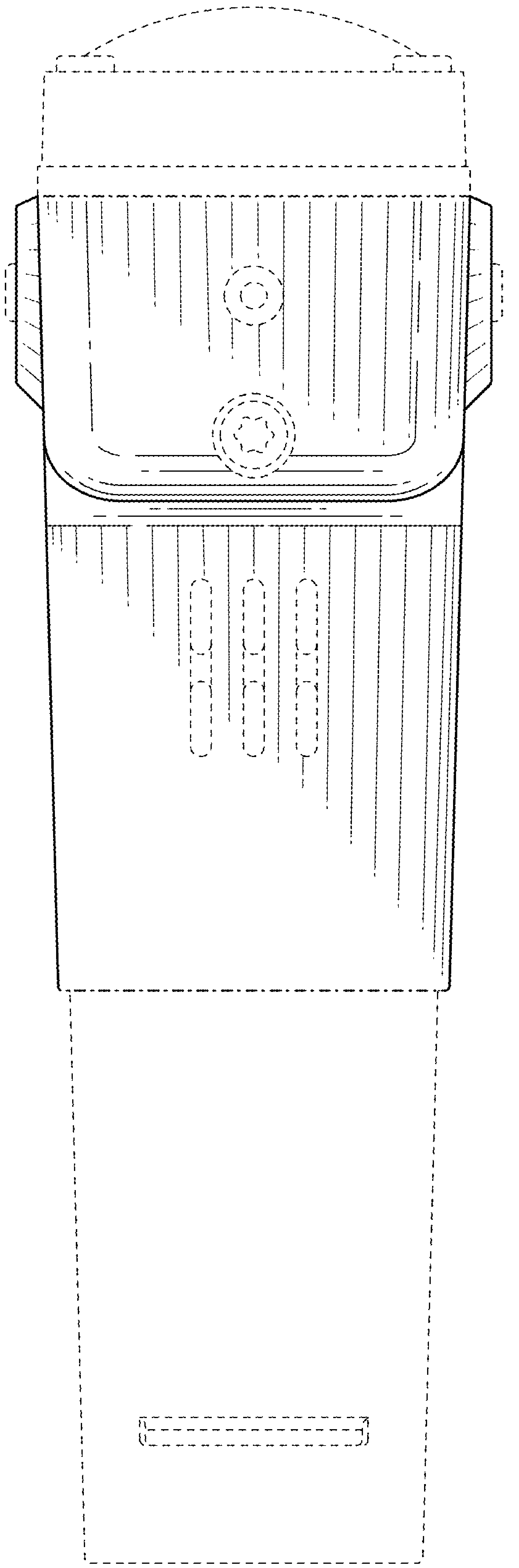

FIG. 8